

Vincent, Stephen C.

Attorney Docket No. P04860US1

Amendments To the Claims

Claims 1-6 (Canceled)

Claim 7 (Currently Amended): A thin film chip resistor comprising:
a substrate;
a single metal thin film resistive layer directly attached to the substrate, the metal thin film layer
being non-tantalum;
a chip resistor termination attached on each end of the metal thin film resistive layer; and
an outer moisture barrier consisting of tantalum pentoxide directly overlaying and contacting the
metal thin film resistive layer for reducing failures due to electrolytic corrosion under
powered moisture conditions; and
the outer moisture barrier formed from deposition of tantalum oxide and not through oxidation of
tantalum.

Claim 8 (Original): The thin film resistor of claim 7 wherein the metal film layer is an alloy
containing nickel.

Claim 9 (Original): The thin film resistor of claim 7 wherein the metal film layer is an alloy
containing chromium.

Claim 10 (Original): The thin film resistor of claim 7 wherein the metal film layer is a nickel-chromium alloy.

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Claim 11 (Canceled)

Claim 12 (Original): The thin film resistor of claim 7 wherein the tantalum pentoxide layer is overlaid by sputtering.

Claim 13 (Currently Amended): A nickel-chromium alloy thin film chip resistor comprising:
an alumina substrate;
a single nickel-chromium alloy thin film layer directly contacting the substrate;
a chip resistor termination attached on each end of the nickel-chromium alloy thin film; and
an outer moisture barrier consisting of tantalum pentoxide directly overlaying and contacting the nickel-chromium alloy thin film layer for reducing failures due to electrolytic corrosion
under powered moisture conditions; and
the outer moisture barrier formed from deposition of tantalum oxide and not through oxidation of tantalum.

Claim 14 (Canceled)

Claim 15 (Currently amended): A nickel-chromium alloy thin film chip resistor comprising:
an alumina substrate;
a single nickel-chromium alloy thin film layer directly contacting the substrate;
a chip resistor termination attached on each end of the nickel-chromium alloy thin film; and
a passivation layer directly overlaying and contacting the nickel-chromium alloy layer; and

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an outer moisture barrier consisting of tantalum pentoxide directly overlaying and contacting the passivation layer for reducing failures due to electrolytic corrosion under powered moisture conditions; and

the outer moisture barrier formed from deposition of tantalum oxide and not through oxidation of tantalum.

Claim 16 (Canceled)